

Chip Lead-Free Removal Alloy (16 feet, 0.8mm THIN Diameter) for SMD/SMT (30-6.5" sticks)

Product Highlights


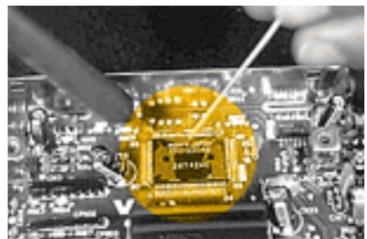


Easily remove SMD parts with **Chip Quik®** removal alloy
 Reduce heat and reduce damage to circuit boards and SMD parts during removal
 Comes with SMDLT flux
RoHS 3 and REACH compliant

Specifications

Alloy:	Chip Quik® Alloy Lead-Free 30-6.5in. Thin Sticks
Alloy Melting Point:	79-91°C (174-195°F)
Thickness:	0.8mm (0.031")
Flux:	SMDLT 2cc/2g Squeeze Tube
Flux Type:	No-Clean
Flux Classification:	RELO
Flux Activation Temperature:	100°C (212°F)



Chip Quik® Instructions

	1	Apply Chip Quik flux to all leads of SMD with syringe or flux applicator.
	2	Melt Chip Quik low temperature alloy uniformly on all pins of SMD. Maintain alloy in molten state long enough for complete reflow.
	3	Lift chip from board with dental pick or vacuum pen.
	4	Thoroughly clean site with swab dipped in flux while applying heat. Clean thoroughly with alcohol pad.

SMD Removal

(With solder iron or warm air bath)

- Apply flux to all leads.
- Melt CHIP QUIK® uniformly on all pins.
- Maintain alloy in molten state long enough to release chip.
- Lift chip from board with dental pick or vacuum pen.

CLEAN UP

- While molten, use cotton swab and flux to move excess to an unused section of board.
- While applying heat, polish each pad with a swab and flux until thoroughly clean.
- At room temperature, clean residue with alcohol pad.
- You are now ready to install the new chip.

5 ft of thin sticks of Chip Quik® material, removes 1250 to 1500 SMD pins.

Conforms to the following Industry Standards:

J-STD-006C, Amendments 1 & 2 (Solder Alloys and Fluxed/Non-Fluxed Solders):
RoHS 3 Directive (EU) 2015/863:

Yes
Yes